

MDR 672E Bandpass 2.45GHz

Multilayer Dielectric Series

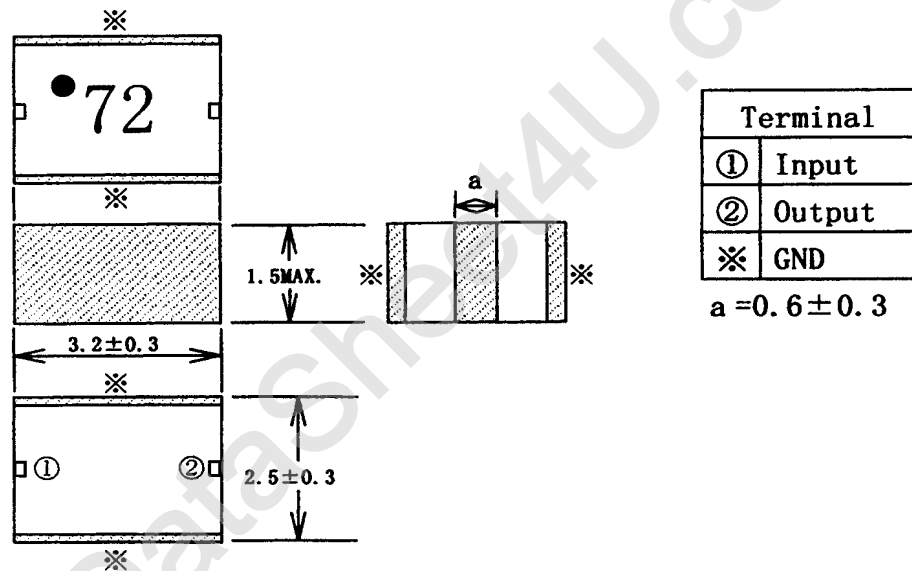
Product Features

- Small size
- Low loss and high attenuation
- SMD and reflow soldering is available

Applications

- Bluetooth / ISM 2.4

Dimension (Unit : mm)



Electrical Characteristics

- 1. Z_{in} & Z_{out} : 50Ω Nominal
- 2. f_c : 2450MHz Nominal
- 3. Pass Band : 2400~2500MHz
- 4. Insertion Loss : 2.1 dB MAX. (2400~2500MHz :at 25°C)
: 2.3 dB MAX. (2400~2500MHz :-40~85°C)
- 5. Ripple : 0.8 dB MAX. (2400~2500MHz)
- 6. V. S. W. R : 2.0 MAX. (2400~2500MHz)
- 7. Attenuation : 48 dB MIN. (880~ 915MHz)
: 49 dB MIN. (1710~1785MHz)
: 40 dB MIN. (1785~1950MHz)
: 35 dB MIN. (at 2100MHz)
: 30 dB MIN. (4800~5000MHz)

Minimum Ordering Quantity : 2,000pcs (per reel, per bag)

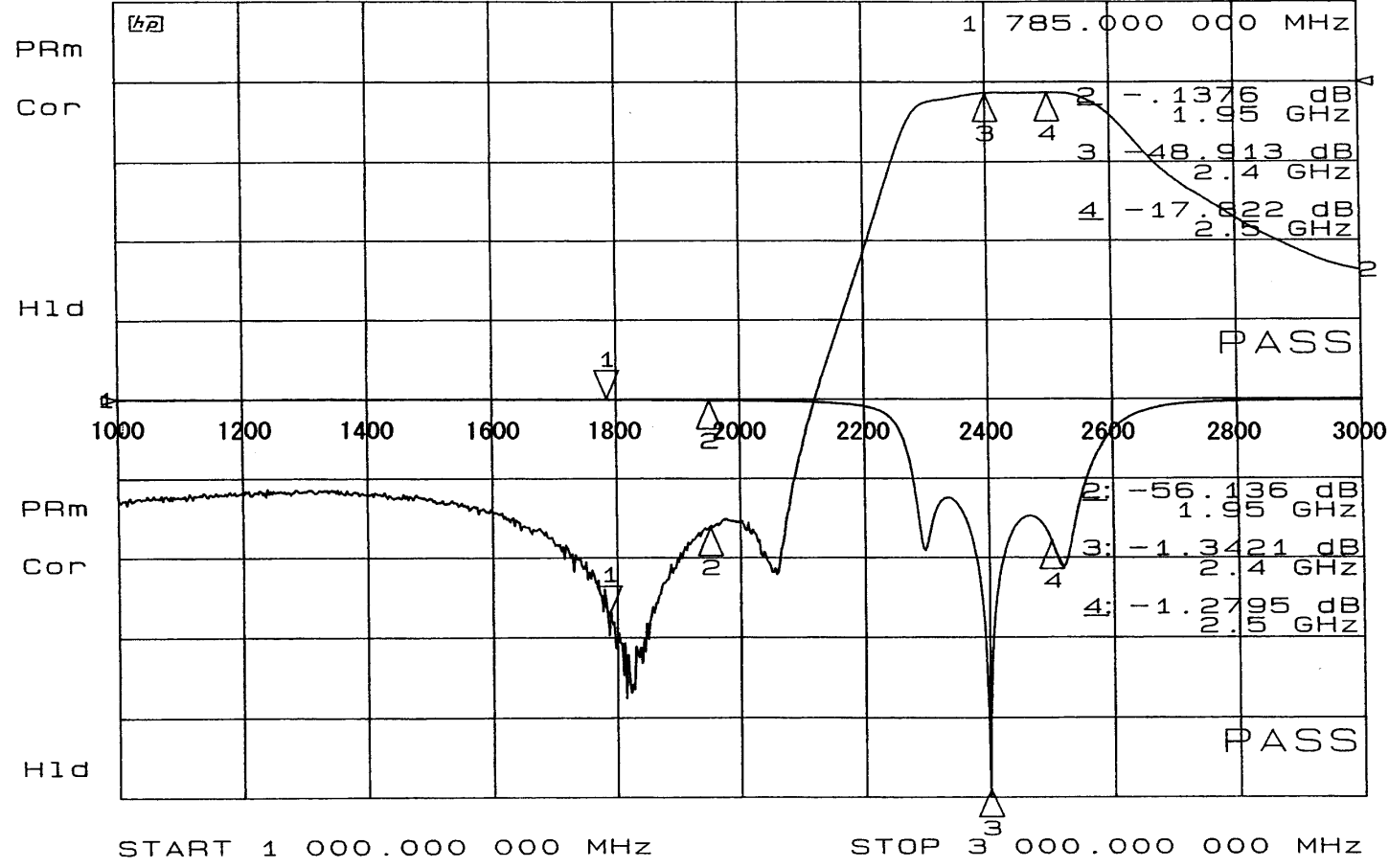


MULTILAYERED FILTERS

MDR672E



CH1 S₁₁ log MAG 10 dB/ REF 0 dB 1: -.0361 dB
 CH2 S₂₁/M log MAG 10 dB/ REF 0 dB 1: -67.142 dB



TYPE
MDR672E

CH1 (S11)
MARK
1 : 1785 MHz
2 : 1950 MHz
3 : 2400 MHz
4 : 2500 MHz

CH2 (S21)
MARK
1 : 1785 MHz
2 : 1950 MHz
3 : 2400 MHz
4 : 2500 MHz

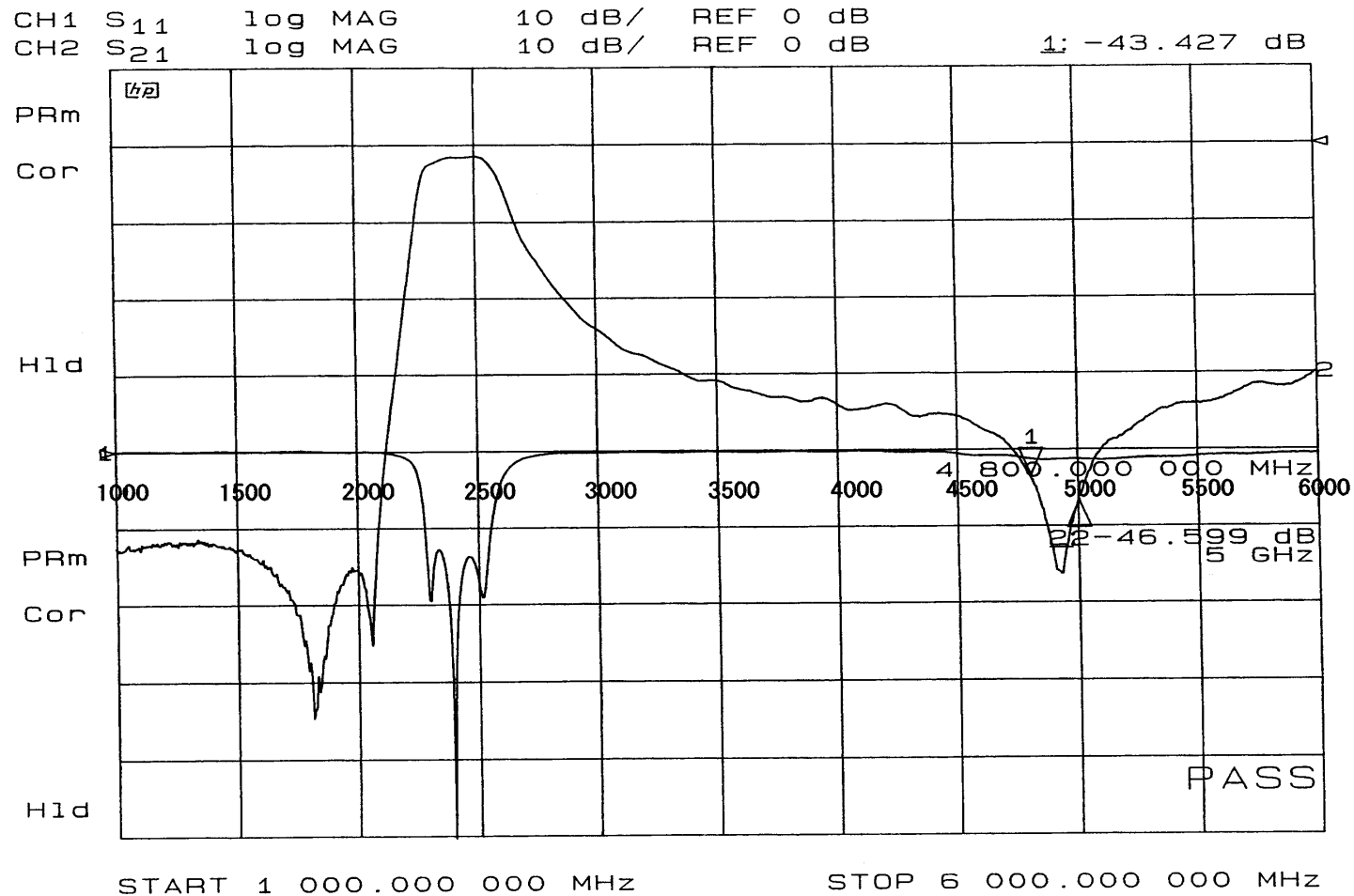
Measurement
Instrument
HP8753D
NETWORK
ANALYZER

Date
2000/11/16
SOSHIN
ELECTRIC
CO., LTD.



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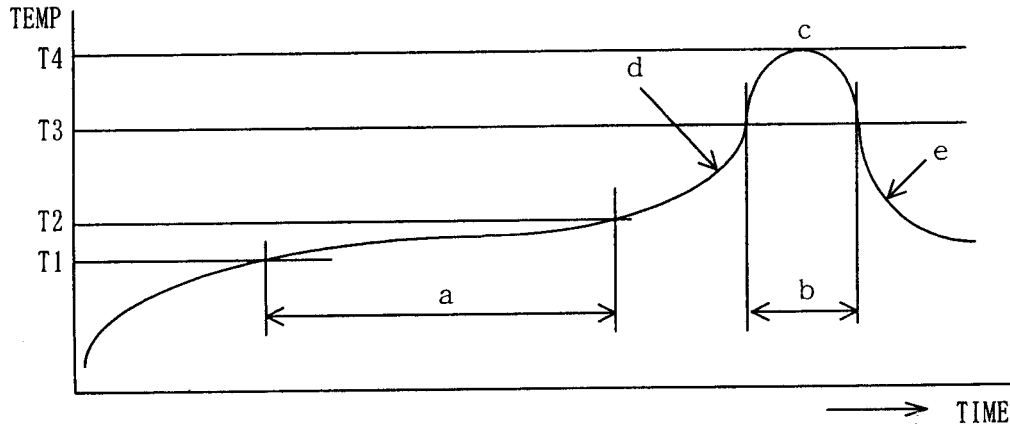
TYPE
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MARK
1 : 4800 MHz
2 : 5000 MHz

Measurement
Instrument
HP8753D
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Reflow-soldering conditions (For reference)



- (1) High temperature reflow-soldering conditions (No more than 2 flows allowed)
- T1 : $130 \pm 10^\circ\text{C}$, T2 : $150 \pm 10^\circ\text{C}$, T3 : 200°C , T4 : 240°C
- a : Preheating 40 to 120 seconds
- b : Heating 50 seconds
- c : Peak temperature 240°C , max.
- d : Temperature rising slope $10^\circ\text{C}/1$ second, max.
- e : Temperature falling slope $8^\circ\text{C}/1$ second, max.

Dip-soldering conditions (For reference)

- (1) Preheating : 100 to 150°C
- (2) Solder bath temperature : $260 \pm 5^\circ\text{C}$
- (3) Dipping time : 5 ± 1 seconds

Cleaning conditions

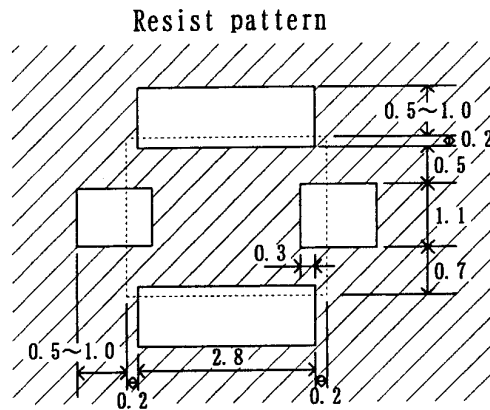
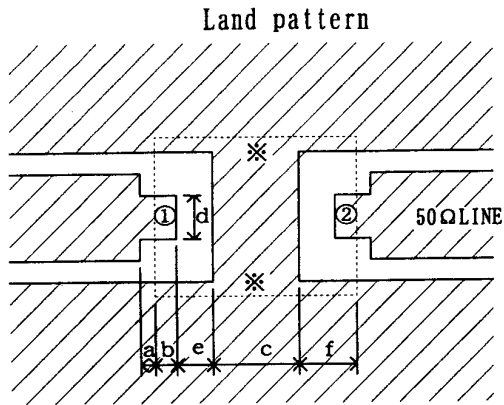
- (1) Cleaning agent : Isopropyl alcohol
- (2) Dip cleaning : 30 minutes, max., at 40°C
- (3) Vapor cleaning : 30 minutes, max.
- (4) Ultrasonic cleaning : 1 minutes, max, with a maximum power of 10w

Recommended Repair Soldering Conditions

- (1) Preheating Conditions
- The temperature difference between soldering iron and device surface must be under 100°C .
- (2) Recommended Condition of Soldering Iron
- ① Power : 20W MAX.
- ② Chip temperature : 270°C MAX.
- ③ Dimension of iron chip : $\sim 1 \phi$
- ④ Soldering time : 3 Seconds MAX.

Recommended application conditions

1. Standard land dimensions (Unit : mm)



Terminal	
①	Input
②	Output
*	GND

a = 0.2
 b = 0.3
 c = 1.6
 d = 0.7
 e = 0.5
 f = 0.8
 (Unit : mm)

Example) t = 1.0mm
 glass-epoxy board